

BUK9Y19-75B

N-channel TrenchMOS logic level FET

Rev. 04 — 13 April 2010

Product data sheet

1. Product profile

1.1 General description

Logic level N-channel enhancement mode Field-Effect Transistor (FET) in a plastic package using TrenchMOS technology. This product has been designed and qualified to the appropriate AEC standard for use in automotive critical applications.

1.2 Features and benefits

- Low conduction losses due to low on-state resistance
- Q101 compliant

- Suitable for logic level gate drive sources
- Suitable for thermally demanding environments due to 175 °C rating

1.3 Applications

- 12 V, 24 V and 42 V loads
- Automotive systems
- DC-to-DC converters
- Engine management

- General purpose power switching
- Motors, lamps and solenoids
- Transmission control

1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V_{DS}	drain-source voltage	$T_j \ge 25 \text{ °C}; T_j \le 175 \text{ °C}$	-	-	75	V
I _D	drain current	V _{GS} = 5 V; T _{mb} = 25 °C; see <u>Figure 1</u> ; see <u>Figure 4</u>	-	-	48.2	Α
P _{tot}	total power dissipation	T _{mb} = 25 °C; see <u>Figure 2</u>	-	-	106	W
Static chara	acteristics					
R _{DSon}	drain-source on-state	$V_{GS} = 5 \text{ V}; I_D = 20 \text{ A};$ $T_j = 25 \text{ °C}; \text{ see } \frac{\text{Figure } 13}{}$	-	15.9	19	mΩ
	resistance	$V_{GS} = 10 \text{ V}; I_D = 20 \text{ A};$ $T_j = 25 \text{ °C}$	-	14.7	18	mΩ



Table 1. Quick reference data ...continued

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Avalanche	ruggedness					
E _{DS(AL)S}	non-repetitive drain-source avalanche energy	$I_D = 48.2 \text{ A}; V_{sup} \le 75 \text{ V};$ $R_{GS} = 50 \Omega; V_{GS} = 5 \text{ V};$ $T_{j(init)} = 25 ^{\circ}\text{C}; \text{ unclamped}$	-	-	121	mJ
Dynamic ch	naracteristics					
Q_{GD}	gate-drain charge	$V_{GS} = 5 \text{ V}; I_{D} = 20 \text{ A};$ $V_{DS} = 60 \text{ V}; T_{j} = 25 \text{ °C};$ see Figure 14	-	12	-	nC

2. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	S	source		
2	S	source	mb	D
3	S	source		
4	G	gate		
mb	D	mounting base; connected to drain	1 2 3 4	mbb076 S
			SOT669 (LFPAK)	

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BUK9Y19-75B	LFPAK	plastic single-ended surface-mounted package (LFPAK); 4 leads	SOT669

4. Limiting values

Table 4. Limiting values

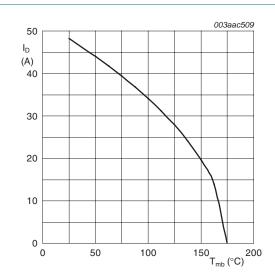
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
V_{DS}	drain-source voltage	T _j ≥ 25 °C; T _j ≤ 175 °C		-	-	75	V
V_{DGR}	drain-gate voltage	$R_{GS} = 20 \text{ k}\Omega; T_{mb} \ge 25 \text{ °C};$ $T_{mb} \le 175 \text{ °C}$		-	-	75	V
V _{GS}	gate-source voltage			-15	-	15	V
I _D	drain current	T_{mb} = 25 °C; V_{GS} = 5 V; see <u>Figure 1</u> ; see <u>Figure 4</u>		-	-	48.2	Α
		T _{mb} = 100 °C; V _{GS} = 5 V; see <u>Figure 1</u>		-	-	34.1	Α
I _{DM}	peak drain current	T_{mb} = 25 °C; t_p ≤ 10 μs; pulsed; see Figure 4		-	-	192	Α
P _{tot}	total power dissipation	T _{mb} = 25 °C; see <u>Figure 2</u>		-	-	106	W
T _{stg}	storage temperature			-55	-	175	°C
Tj	junction temperature			-55	-	175	°C
Source-drain of	diode						
Is	source current	T _{mb} = 25 °C		-	-	48.2	Α
I _{SM}	peak source current	$t_p \le 10 \mu\text{s}; \text{ pulsed}; T_{mb} = 25 ^{\circ}\text{C}$		-	-	192	Α
Avalanche rug	gedness						
E _{DS(AL)S}	non-repetitive drain-source avalanche energy	I_D = 48.2 A; V_{sup} ≤ 75 V; R_{GS} = 50 Ω; V_{GS} = 5 V; $T_{j(init)}$ = 25 °C; unclamped		-	-	121	mJ
E _{DS(AL)R}	repetitive drain-source avalanche energy	see Figure 3	[1][2][3]	-	-	-	J

^[1] Single-pulse avalanche rating limited by maximum junction temperature of 175 $^{\circ}\text{C}.$

^[2] Repetitive avalanche rating limited by average junction temperature of 170 °C.

^[3] Refer to application note AN10273 for further information.



120

P_{der}
(%)

80

40 $P_{der} = \frac{P_{tot}}{P_{tot(25^{\circ}C)}} \times 100\%$

Fig 1. Continuous drain current as a function of mounting base temperature

Fig 2. Normalized total power dissipation as a function of mounting base temperature

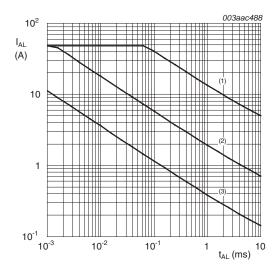
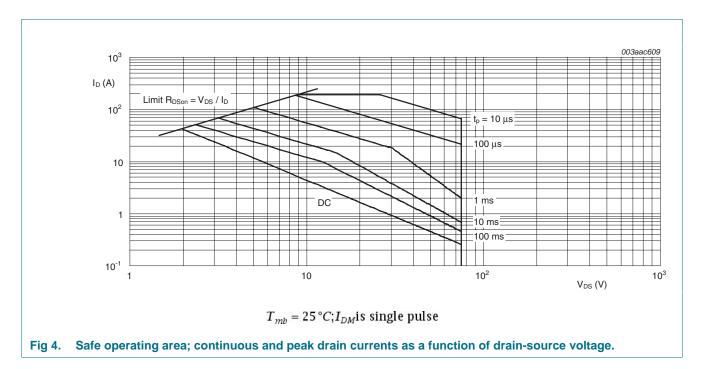


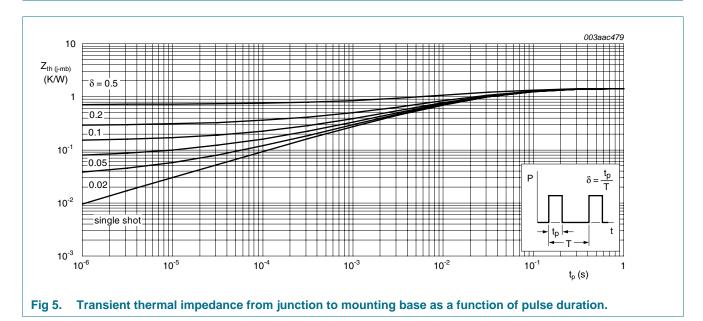
Fig 3. Single-pulse and repetitive avalanche rating; avalanche current as a function of avalanche time



5. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	see Figure 5	-	-	1.42	K/W



6. Characteristics

Table 6. Characteristics

Table 6.	Characteristics					
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static cha	racteristics					
$V_{(BR)DSS}$	drain-source	$I_D = 0.25 \text{ mA}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ °C}$	75	-	-	V
	breakdown voltage	$I_D = 0.25 \text{ mA}; V_{GS} = 0 \text{ V}; T_j = -55 ^{\circ}\text{C}$	70	-	-	V
V _{GS(th)} gate-source threshold voltage	gate-source threshold voltage	$I_D = 1$ mA; $V_{DS} = V_{GS}$; $T_j = 175$ °C; see <u>Figure 10</u> ; see <u>Figure 11</u>	0.5	-	-	V
		I_D = 1 mA; V_{DS} = V_{GS} ; T_j = 25 °C; see <u>Figure 10</u> ; see <u>Figure 11</u>	1.25	1.65	2.15	V
		$I_D = 1$ mA; $V_{DS} = V_{GS}$; $T_j = -55$ °C; see <u>Figure 10</u> ; see <u>Figure 11</u>	-	-	2.45	V
I _{DSS}	drain leakage current	$V_{DS} = 75 \text{ V}; V_{GS} = 0 \text{ V}; T_j = 175 \text{ °C}$	-	-	500	μΑ
		$V_{DS} = 75 \text{ V}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ °C}$	-	0.02	1	μΑ
I _{GSS} gate leakage current	gate leakage current	V _{DS} = 0 V; V _{GS} = +15 V; T _j = 25 °C	-	2	100	nA
		V _{DS} = 0 V; V _{GS} = -15 V; T _j = 25 °C	-	2	100	nA
R _{DSon} drain-source on-state resistance	drain-source on-state	V _{GS} = 4.5 V; I _D = 20 A; T _j = 25 °C	-	-	21	mΩ
	$V_{GS} = 5 \text{ V}; I_D = 20 \text{ A}; T_j = 175 °C;$ see Figure 12	-	-	48	mΩ	
		$V_{GS} = 5 \text{ V}; I_D = 20 \text{ A}; T_j = 25 ^{\circ}\text{C};$ see Figure 13	-	15.9	19	mΩ
		V _{GS} = 10 V; I _D = 20 A; T _i = 25 °C	-	14.7	18	mΩ
Dynamic o	characteristics	·				
Q _{G(tot)}	total gate charge	$I_D = 20 \text{ A}; V_{DS} = 60 \text{ V}; V_{GS} = 5 \text{ V};$	-	30	-	nC
Q_{GS}	gate-source charge	T _j = 25 °C; see <u>Figure 14</u>	-	4.9	-	nC
Q_{GD}	gate-drain charge		-	12	-	nC
C _{iss}	input capacitance	$V_{GS} = 0 \text{ V}; V_{DS} = 25 \text{ V}; f = 1 \text{ MHz};$	-	2322	3096	pF
C _{oss}	output capacitance	$T_j = 25$ °C; see <u>Figure 15</u>	-	258	309	pF
C_{rss}	reverse transfer capacitance		-	107	146	pF
t _{d(on)}	turn-on delay time	$V_{DS} = 30 \text{ V}; R_L = 1.5 \Omega; V_{GS} = 5 \text{ V};$	-	13	-	ns
t _r	rise time	$R_{G(ext)} = 10 \Omega; T_j = 25 °C$	-	11	-	ns
d(off)	turn-off delay time		-	77	-	ns
t _f	fall time		-	21	-	ns
Source-dr	ain diode					
V _{SD}	source-drain voltage	$I_S = 20 \text{ A}$; $V_{GS} = 0 \text{ V}$; $T_j = 25 \text{ °C}$; see Figure 16	-	0.85	1.2	V
·rr	reverse recovery time	$I_S = 20 \text{ A}; dI_S/dt = -100 \text{ A/}\mu\text{s};$	-	57	-	ns
Q _r	recovered charge	$V_{GS} = -10 \text{ V}; V_{DS} = 30 \text{ V}; T_j = 25 \text{ °C}$	-	145	-	nC

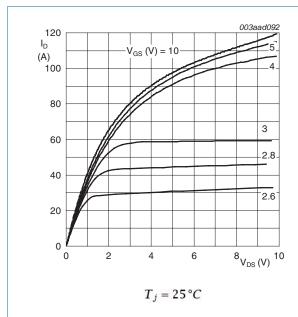


Fig 6. Output characteristics: drain current as a function of drain-source voltage; typical values

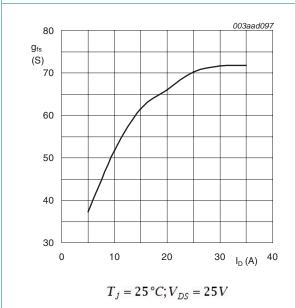


Fig 8. Forward transconductance as a function of drain current; typical values

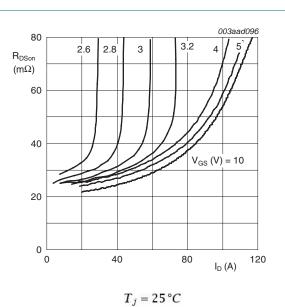


Fig 7. Drain-source on-state resistance as a function of drain current; typical values

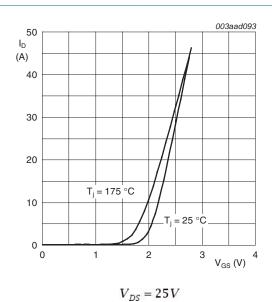


Fig 9. Transfer characteristics: drain current as a function of gate-source voltage; typical values

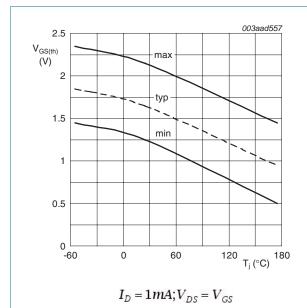


Fig 10. Gate-source threshold voltage as a function of junction temperature

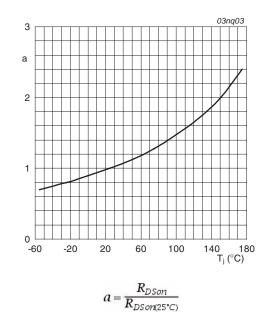
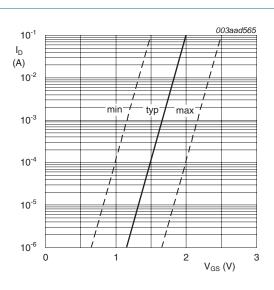
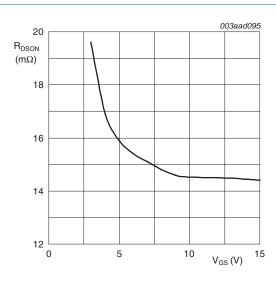


Fig 12. Normalized drain-source on-state resistance factor as a function of junction temperature



 $T_j = 25\,^{\circ}C; V_{DS} = V_{GS}$

Fig 11. Sub-threshold drain current as a function of gate-source voltage



 $T_j = 25\,^{\circ}C; I_D = 20A$

Fig 13. Drain-source on-state resistance as a function of gate-source voltage; typical values

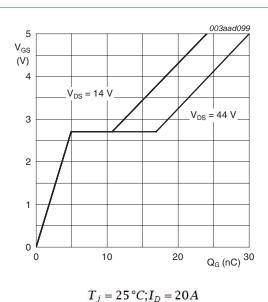
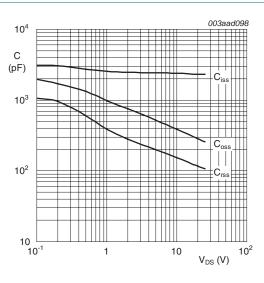


Fig 14. Gate-source voltage as a function of gate charge; typical values



 $V_{GS} = 0V; f = 1MHz$

Fig 15. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

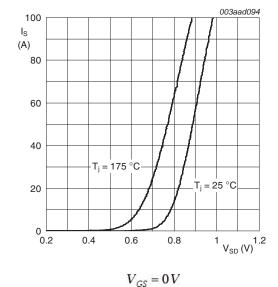


Fig 16. Source current as a function of source-drain voltage; typical values

7. Package outline

Plastic single-ended surface-mounted package (LFPAK); 4 leads **SOT669** С c₂- E_1 mounting b₄ base D_1 D Х **→** w M A е 1/2 e (A_3) С detail X 5 mm scale **DIMENSIONS (mm are the original dimensions)** D₁⁽¹⁾ A₂ D⁽¹⁾ E⁽¹⁾ UNIT Α b b_2 b_3 b_4 E₁⁽¹⁾ L L_2 θ Α₁ A₃ С c_2 е L_1 у 1.20 0.15 1.10 0.50 4.41 0.9 0.25 0.30 4.10 3.3 6.2 0.85 1.3 1.27 0.25 0.00 0.95 0.35 3.62 2.0 0.7 0.19 0.24 3.80 0.40 8.0 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

Fig 17. Package outline SOT669 (LFPAK)

IEC

BUK9Y19-75B

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REFERENCES

JEDEC

MO-235

ISSUE DATE

04-10-13

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VERSION

SOT669

8. Revision history

Table 7. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BUK9Y19-75B_4	20100413	Product data sheet	-	BUK9Y19-75B_3
Modifications:	 Status char 	nged from objective to pro	oduct.	
BUK9Y19-75B_3	20100216	Objective data sheet	-	BUK9Y19-75B_2

9. Legal information

9.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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Product [short] data sheet	Production	This document contains the product specification.

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N-channel TrenchMOS logic level FET

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